

Customer:

Product Change Notice (PCN Tracking Number: EE-QR-220119-01)

ALL Customers

Version: 1

Renesas Product Ty	r pe: M16C & M32	M16C & M32C. Refer to separate file "Product List & Change Scenario.xlsx"			
Description of Chan	ge: Change of di	Change of die attach material, lead frame and production factory (pages 2-4)			
Reason for Change:	Due to the er	Due to the end of supply by the material manufacturer			
Identification:	Identifiable vi	Identifiable via production history data from the trace code			
Sample delive Reliability rep Requested ap		port: available (upon r	• ,		
Anticipated Impact:		Fit, Form & Function: Quality & Reliability: No change No impact			
Doc. No.:	EEQC-PCN-	EEQC-PCN-CR-22-0039			
Internal Reference:	IMO-AZ-21-0	0003-1			
In case of any question	n, please contact:				
INITIATOR	TITLE	E-mail	PHONE No.		
Farhad Banihashemi	Staff Engineer	farhad.banihashemi@renes	as.com +49-211-6503-1844		
□ acknowledge□ acceptable□ inacceptable (pls. on applicable	urn by e-mail, fax or m C comment) Name & Phone /	Position: Fax No.:			
of receipt of this PCN in PCN within 90 days of	in which to make any ob the receipt of the PCN	bjections to the PCN. If Custo then Renesas will consider the	mer shall have 90 days from the date mer fails to make objections to this e PCN changes as approved. If ne buy demand and purchase order.		



Details of Change:

Factory:

Before: Amkor Technology Japan, Inc. & Renesas Semiconductor (Beijing) Co., Ltd.

After: Amkor Technology Japan, Inc.

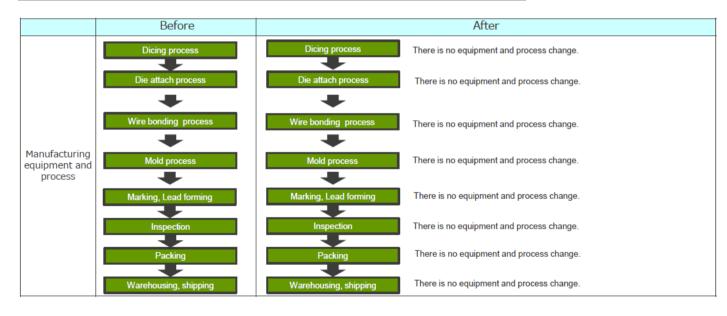
Die attach material: (Film →Ag paste)

Lead frame: (Fe →Cu, no change in shape.)

ltem		Before	After
Die attach material	material	Film die attach	Ag paste die attach
Lead Frame	Raw material	Fe	Cu
Shape		No Change	

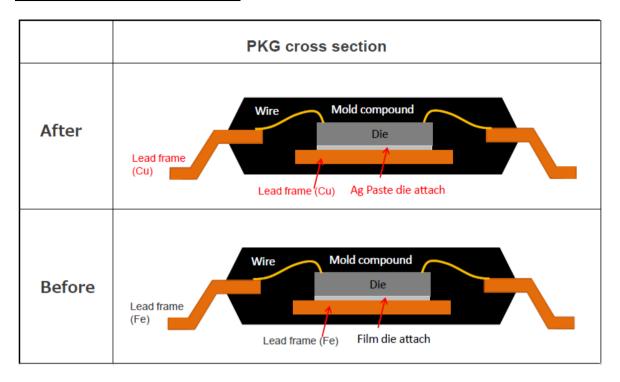
The changed material has a track record of mass production showing no change in reliability and characteristics.

Changes in Manufacturing Equipment and Manufacturing Process:

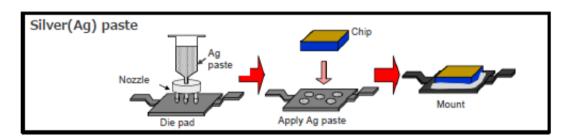


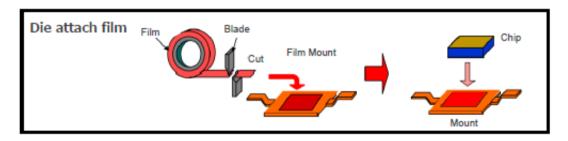


Package Structure (example):



Ag Paste /Die Attach Film Process (Image):







4M Changing Point Comparison:

Item	Check Result	Judg ment
Machine	The manufacturing equipment has not changed.	No risk
Method	The manufacturing method has not changed.	
Man	A worker certification system has been introduced and only workers who have received education and certification are engaged.	No risk
Material	Only Ag paste die attach material certified by OSAT will be used. The Ag paste die attach material to be changed has a track record of mass production. Only lead frame certified by OSAT will be used. The lead frame to be changed has a track record of mass production. We have confirmed that there is no problem with quality.	No risk

Changing point	Failure mode	factor	At process establishment	Judgment
Die attach material change	Chip support failure	by poor curing	same PKG outline.	No risk
	Impact on reliability	Delamination after reflow	Reliability evaluation with similar products with the same PKG outline is no problem.	No risk
The material of lead frame change	Assembly failure	Die misaligned	Mass productivity was evaluated using representative products with the same PKG outline.	No risk
	Impact on reliability	Delamination after reflow	Reliability evaluation with representative products with the same PKG outline is no problem.	No risk

Product List:

Please refer to separate file "Product List & Change Scenario.xlsx"